Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-46 (Canceled)

Claim 47 (Currently amended): A burn-in apparatus for ~~burning-in~~ burning in semiconductor devices, comprising:

a semiconductor wafer comprising a plurality of unsingulated semiconductor devices on the wafer, each said semiconductor device comprising a plurality of resilient contact structures ~~mounted thereon~~ attached to terminals of said semiconductor device;

a test board disposed in proximity to said semiconductor wafer, said test board comprising a plurality of contact elements~~, said test board disposed in proximity to said semiconductor wafer,~~ for forming pressure connections between ones of said resilient contact structures and corresponding contact elements of said test board; and

means for elevating a temperature of said semiconductor devices for a period of time.

Claim 48 (Previously presented): The burn-in apparatus of claim 47 wherein said test board comprises a printed circuit board.

Claim 49 (Previously presented): The burn-in apparatus of claim 47 wherein said contact elements of said test board further comprise a plurality of terminals mounted adjacent said test board.

Claim 50 (Previously presented): The burn-in apparatus of claim 47 further comprising means for positioning said wafer and said test board so that corresponding resilient contact structures and contact elements are aligned.

Claim 51 (Previously presented): The burn-in apparatus of claim 47 further comprising means for positioning said wafer and said test board so that corresponding resilient contact structures and contact elements are compressed together to form said pressure connections.

Claim 52 (Previously presented): The burn-in apparatus of claim 47, wherein said means for elevating is capable of elevating said temperature of said semiconductor devices to least 125° C.

Claim 53 (Previously presented): The burn-in apparatus of claim 47, wherein said means for elevating is capable of elevating said temperature of said semiconductor devices to least 150° C.

Claim 54 (Previously presented): The burn-in apparatus of claim 47, wherein said means for elevating is capable of elevating said temperature of said semiconductor devices to least 175° C.

Claim 55 (Previously presented): The burn-in apparatus of claim 47, wherein said means for elevating is capable of elevating said temperature of said semiconductor devices to least 200° C.

Claim 56 (Currently amended): The burn-in apparatus of claim 47, wherein each of said plurality of resilient contact structures comprises:

(i) an attachment portion attached to a ~~corresponding~~ terminal of one of said semiconductor devices,

(ii) a resilient section, having an elongate springable shape, extending from said attachment portion, and

(iii) a contact region remote from said semiconductor device, and

said resilient contact structure being free standing and said contact region being depressible towards said semiconductor wafer due to resilient spring action of said resilient section.

Claim 57 (Previously presented): The burn-in apparatus of claim 56, wherein said contact region comprises a contact tip structure joined to said resilient contact structure.

Claim 58 (Previously presented): The burn-in apparatus of claim 47 further comprising means for testing functionality of at least one of said semiconductor devices while at an elevated temperature.

Claim 59 (Previously presented): The burn-in apparatus of claim 47 further comprising means for testing a plurality of operating parameters of said semiconductor devices while at an elevated temperature.

Claims 60-65 (Canceled)

Claim 66 (New): The burn-in apparatus of claim 56, wherein a length of said resilient section between said attachment portion and said contact region is more than twice a width of said resilient section.

Claim 67 (New): The burn-in apparatus of claim 56, wherein said contact region comprises a tip of said resilient contact structure.

Claim 68 (New): The burn-in apparatus of claim 67, wherein each contact structure comprises a plurality of structurally distinct elements attached one to another, wherein said tip is one of said structurally distinct elements.

Claim 69 (New): The burn-in apparatus of claim 47, wherein each of said plurality of resilient contact structures is elongate.

Claim 70 (New): The burn-in apparatus of claim 47, wherein each of said plurality of resilient contact structures comprises a free standing electrical conductor.

Claim 71 (New): The burn-in apparatus of claim 47, wherein each of said plurality of resilient contact structures comprises an electrically conductive structure, and said electrically conductive structure is a spring.

Claim 72 (New): The burn-in apparatus of claim 47, wherein said semiconductor devices are unpackaged dies.